SOT804-3(D)

HVQFN64, thermal enhanced very thin quad flat package, no leads, dimple wettable flank; 64 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

7 September 2018 **Package information**

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN64
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	20-07-2018
Manufacturer package code	98ASA01298D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	

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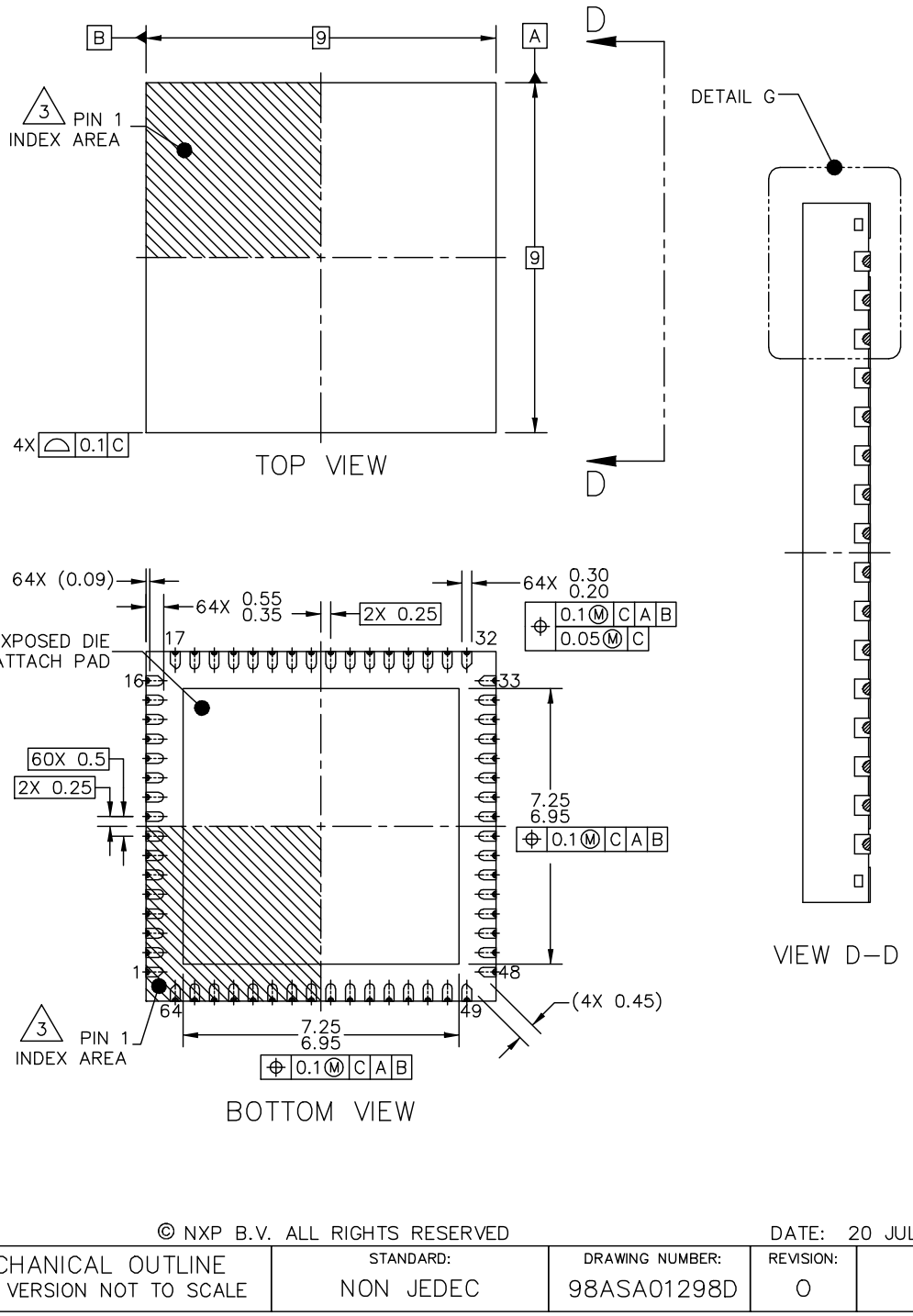
2 Package outline

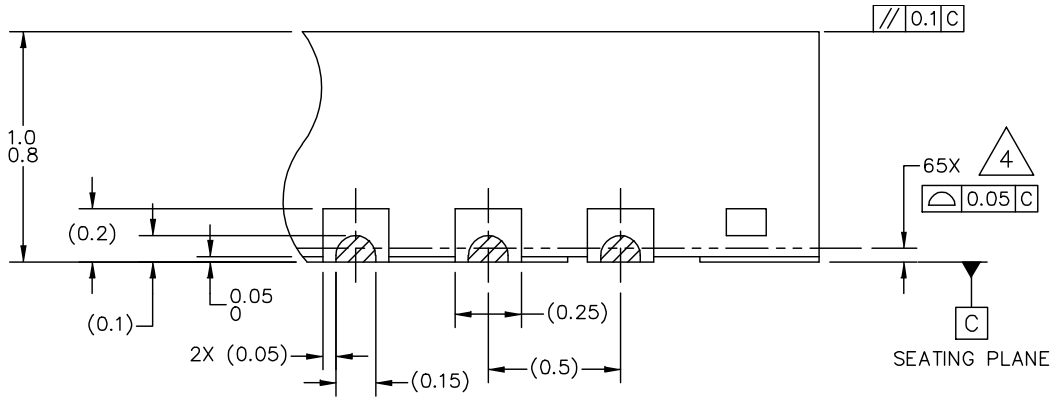


DATE: 20 JUL 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01298D	REVISION: O	

Figure 1. Package outline HVQFN64 (SOT804-3(D))

HVQFN64, thermal enhanced very thin quad flat package, no leads, dimple wettable flank; 64 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body



DETAIL G
VIEW ROTATED 90° CW

DATE: 20 JUL 2018

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Figure 2. Package outline detail HVQFN64 (SOT804-3(D))

3 Soldering

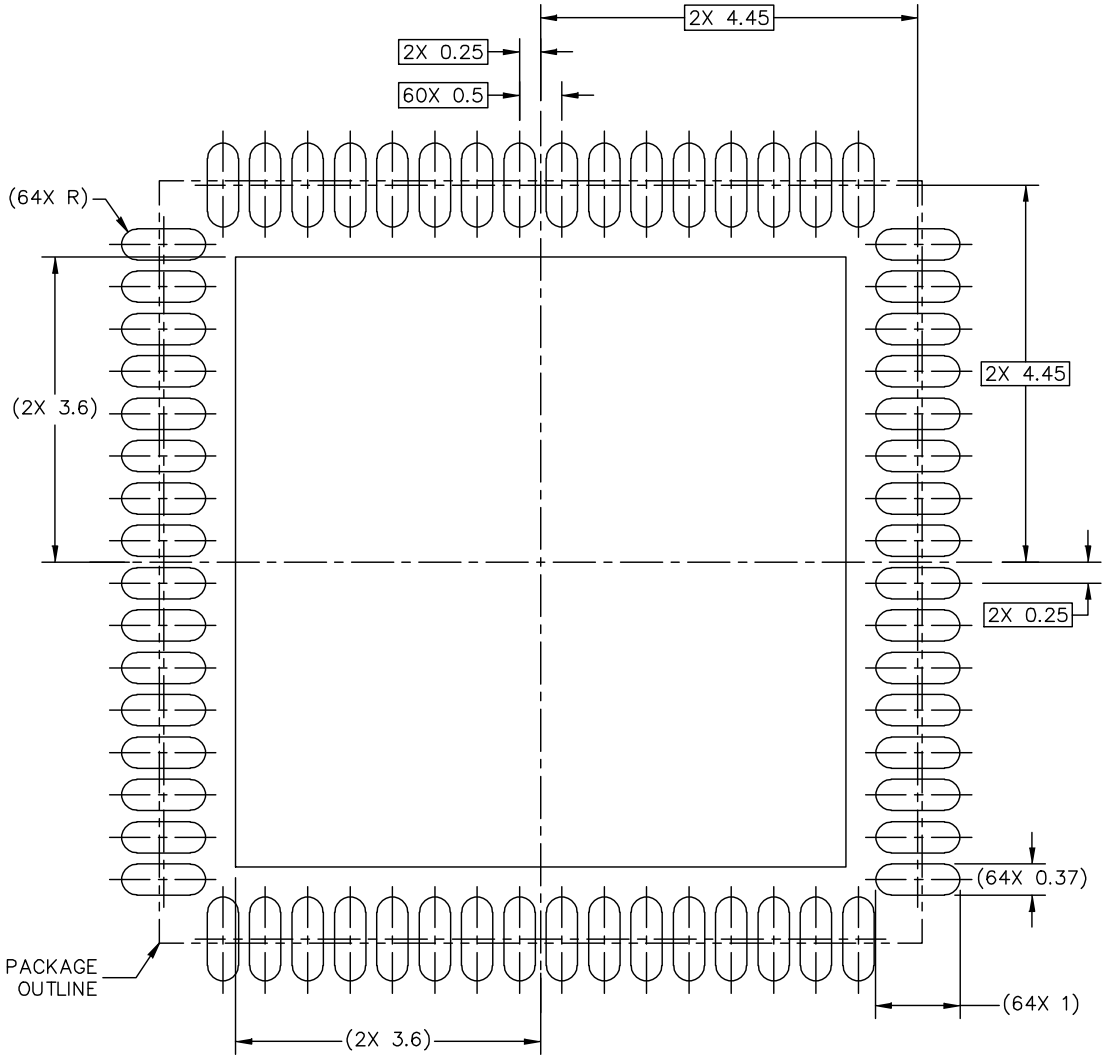
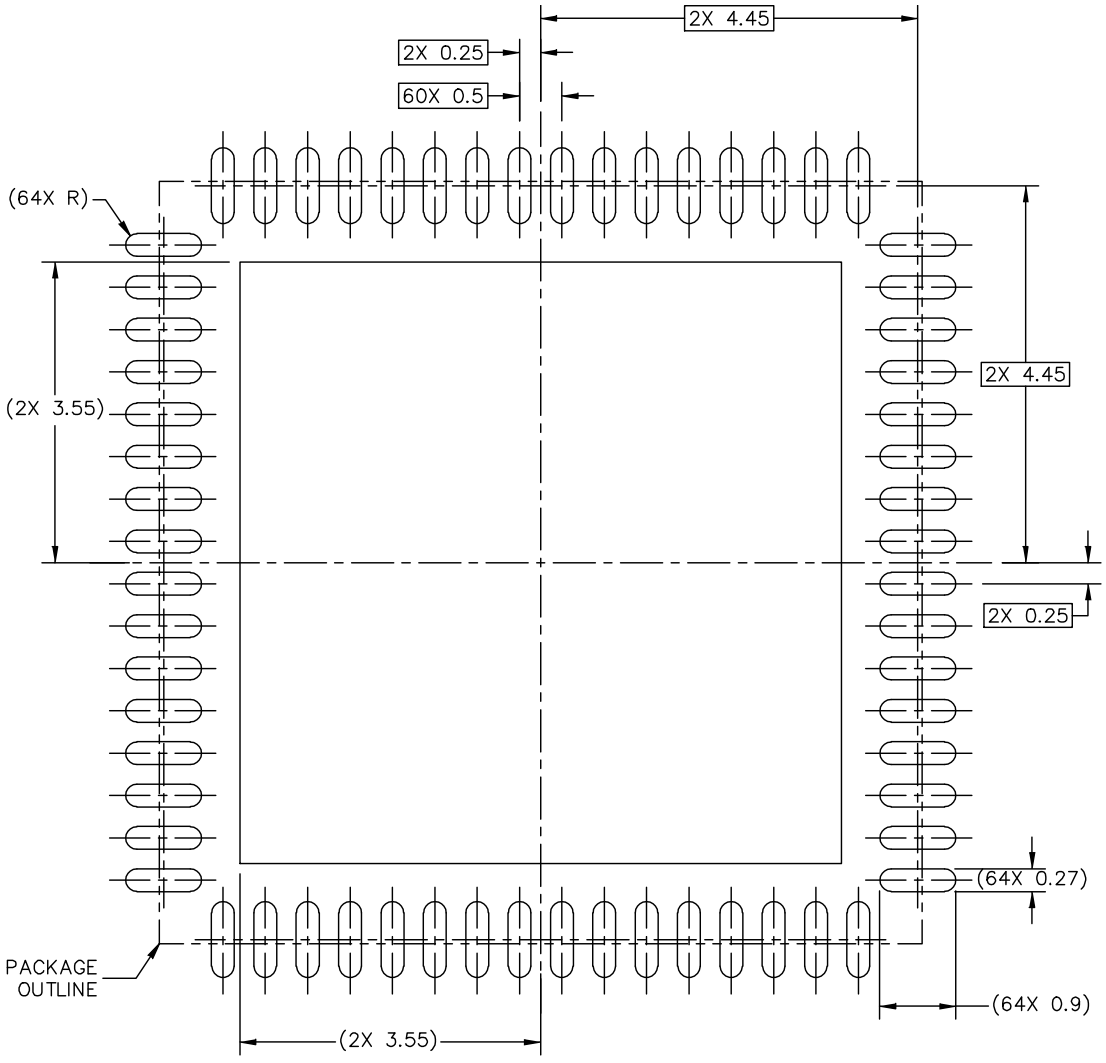


Figure 3. Reflow soldering footprint part1 for HVQFN64 (SOT804-3(D))



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 20 JUL 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01298D	REVISION: O	

Figure 4. Reflow soldering footprint part2 for HVQFN64 (SOT804-3(D))

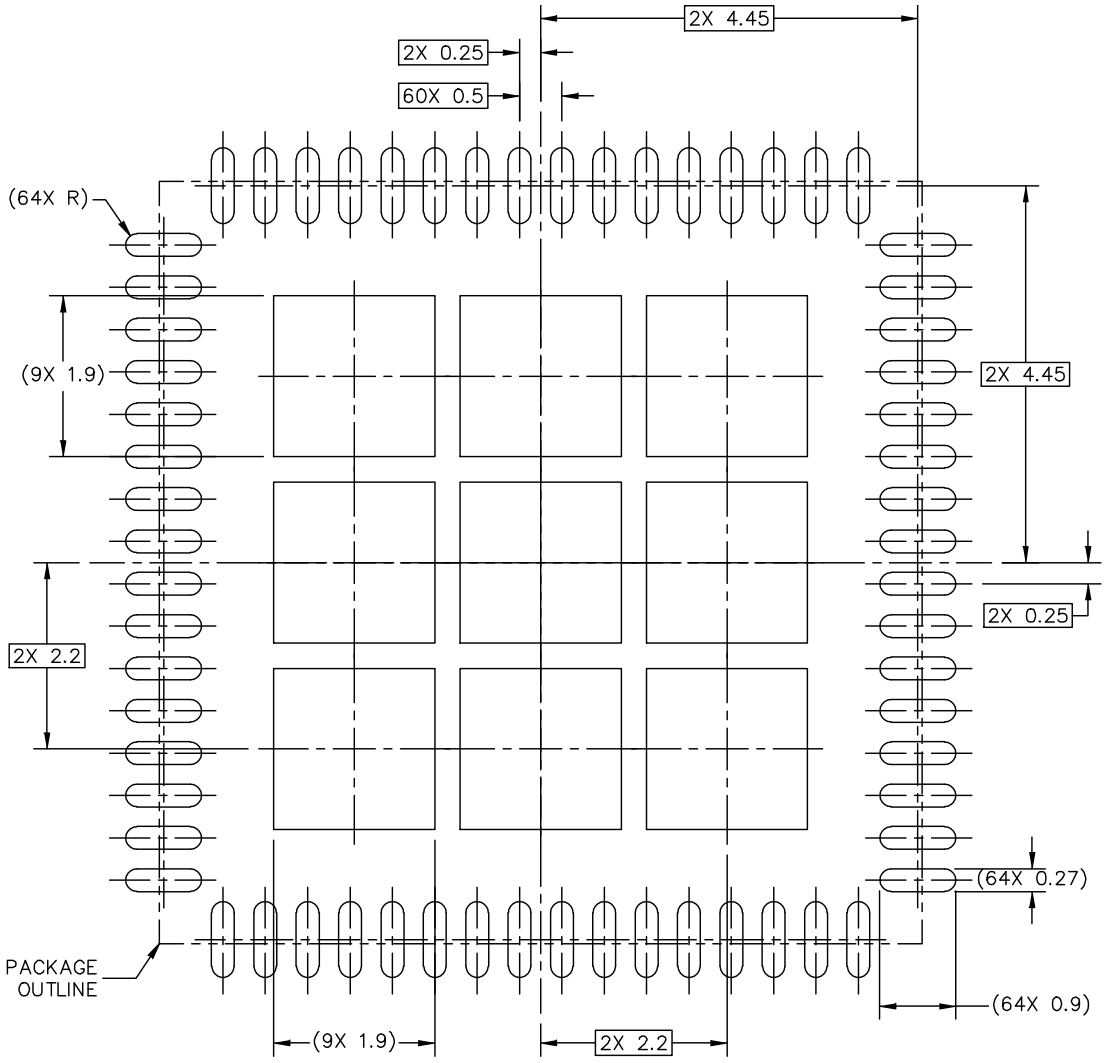


Figure 5. Reflow soldering footprint part3 for HVQFN64 (SOT804-3(D))

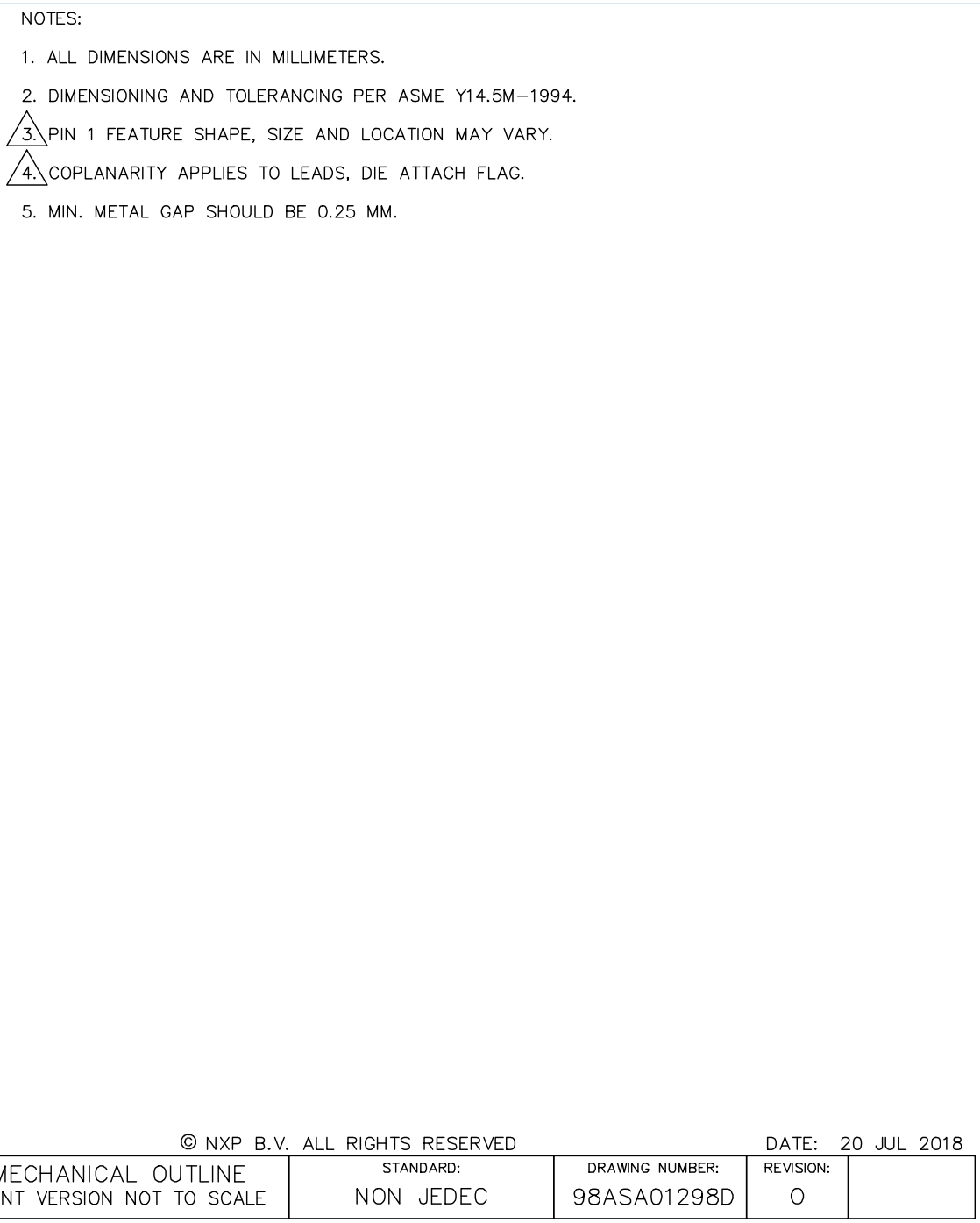


Figure 6. Package outline note HVQFN64 (SOT804-3(D))

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Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com
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